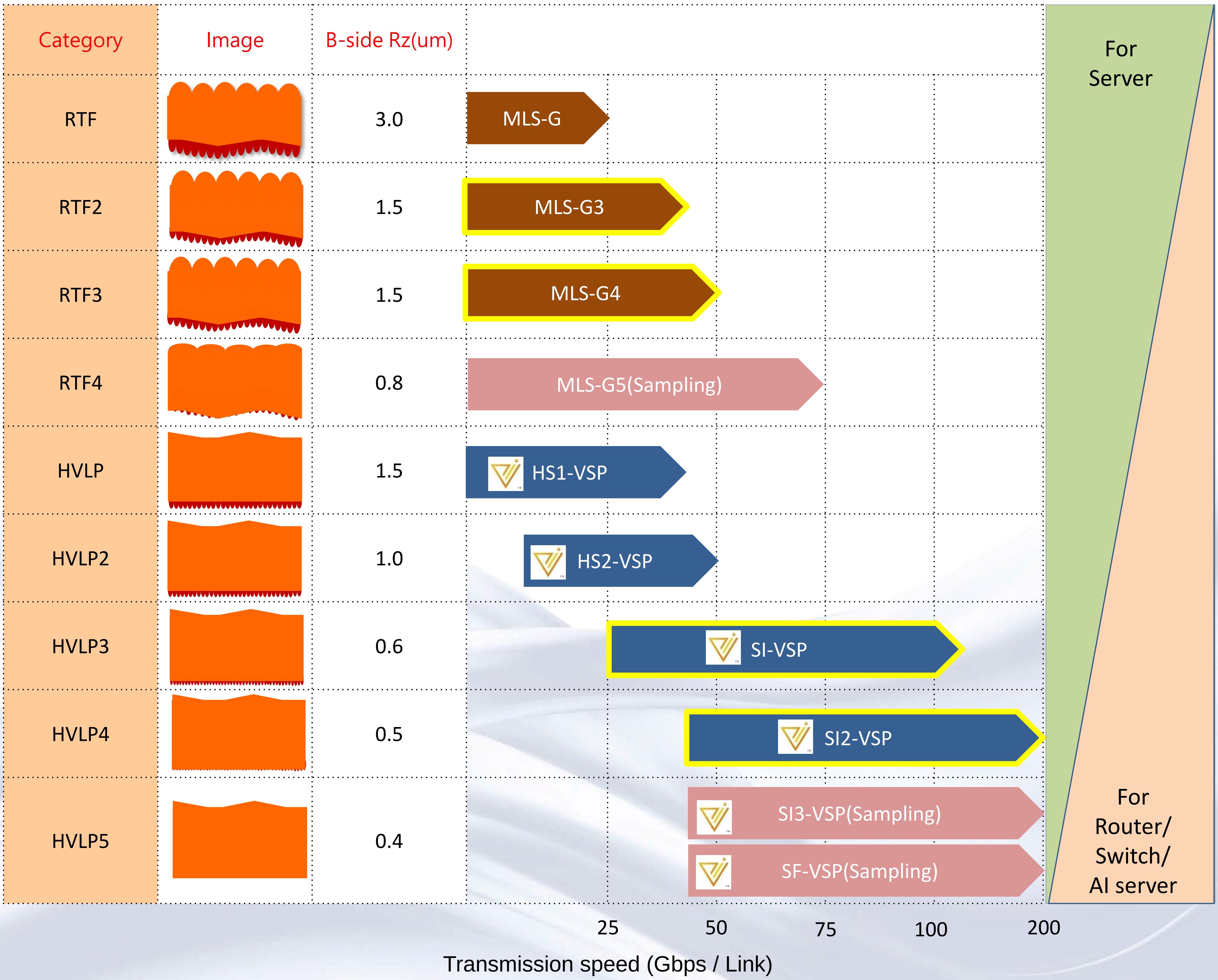
Mitsui HSD Application Foil Roadmap

三井金属

高頻高速(HSD)用銅箔

Copper foil for the HSD(High Speed Digital) application

- 針對更加高頻高速的需求,發展更低耗損的銅箔材料.
- Developing copper foil that achieve sufficiently low loss to meet increasing demand for higher-speed transmission.
- 多樣化的樹脂匹配性,運用獨有的技術來達到低耗損及良好結合力的目標.
- Achieved both low loss and sufficient adhesion reliability for diversified resin systems by applying our unique technology.



Category	Image	B-side Rz(um)	
RTF		3.0	MLS-G
RTF2		1.5	MLS-G3
RTF3		1.5	MLS-G4
RTF4		0.8	MLS-G5(Sampling)
HVLP		1.5	HS1-VSP
HVLP2		1.0	HS2-VSP
HVLP3		0.6	SI-VSP
HVLP4		0.5	SI2-VSP
HVLP5		0.4	SI3-VSP(Sampling) SF-VSP(Sampling)

*上述表列為代表性資料,非保証值. * This is representative data not guarantee